



# 24<sup>th</sup> IEEE European Test Symposium

Baden-Baden, Germany

May 27 – 31, 2019

<http://www.ieee-ets.org>



## Call for Submissions – *Vendor Sessions and Table-Top Demos*

The IEEE European Test Symposium (ETS) is Europe's premier forum dedicated to presenting and discussing scientific results, industrial application results, emerging ideas, applications, hot topics, and new trends in the area of electronic-based circuits and system testing and reliability. ETS is organized annually in a different European country. In 2019, ETS will be held in Baden-Baden, Germany, and will take place May 27-31. ETS is the nucleus of the European Test Week which includes TSS (Test Spring School), fringe workshops, and fringe meetings.

ETS offers commercial vendors the opportunity to give technical presentations in **Vendor Sessions** in a track parallel to the regular paper sessions. Typical content includes product descriptions, case studies, best practices, and user testimonials of products or solutions. ETS also offers the opportunity for **Table Top Demos** during the event. Table Top Demo participants get a table, poster board, and electricity outlet provided by ETS. A Table Top Demo may include displaying slides and/or demoing tools or products.

These presentations will be listed in the symposium program along with the other sessions, and should be targeted to ETS' technical audience. Vendor Sessions and Table Top Demos differ from other ETS presentations in that company names, logos, and product names may be mentioned explicitly. Proposal selection is based on technical content and relevance to ETS audience and topics. Available slots will be assigned in a first-come-first-served order, but priority will be given to Corporate Supporters with higher priority for higher support grades. The areas of interest include (but are not limited to) the following topics:

- Analog Test
- ATE Hardware and Software
- Automatic Test Generation
- Board Test and Diagnosis
- Boundary Scan Test
- Built-In Self-Test (BIST)
- Current-Based Test
- Defect-Based Test
- Delay and Performance Test
- Dependability and Functional Safety
- Design for Test (DfT)
- Design for Manufacturing (DfM)
- Diagnosis and Silicon Debug
- Economics of Test
- Emerging Technologies
- Failure Analysis
- Fault Modeling and Simulation
- Fault Tolerance
- GPU Test
- High-Speed I/O Test
- Low-Power IC Test
- Memory Test and Repair
- MEMS Test
- Microprocessor Test
- Mixed-Signal Test
- Multi-/Many-core Processor Test
- Nanotechnology Test
- On-line Test
- Power Issues in Test
- Reconfigurable System Test
- Reliability
- RF Test
- Security and Trust Issues in Test
- Self-Repair
- Sensor Test
- Signal Integrity Test
- SiP, Stacked, 3D IC Test
- SoC Test
- Soft Errors
- Standards in Test
- System Test
- Test Compression
- Test Quality
- Test Synthesis
- Thermal Issues in Test
- Validation and Verification
- Variability Issues in Test
- Yield Analysis and Enhancement

### Submissions

Submission of proposals for ETS'19 Vendor Session or Table-Top Demo presentations can be an abstract, extended abstract, or full paper (max. six pages); submission of a full paper is preferred, but not required. Proposals should be submitted via the ETS'19 website; detailed submissions instructions can also be found there (go to <http://www.ieee-ets.org>, follow the link to ETS'19, and then select the appropriate call). Key dates for submissions:

- Submission deadline (for VS/TTD's only): **January 30, 2019**
- Notification of acceptance: **February 15, 2019**
- Camera-ready manuscript: **March 22, 2019**

### ETS'19 Corporate Support

Every year, ETS is financially supported by several companies. The support money is used to cover costs associated with ETS and make the event accessible to even more attendees. In return, the corporate supporters are allowed to make publicity in various ways. ETS has defined four different support grades (Bronze, Silver, Gold, and Platinum), each with different support amounts and publicity options. To find out more, contact Juergen Schloeffel or Hans Manhaeve, details below.

### More Information

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